

# 客户图

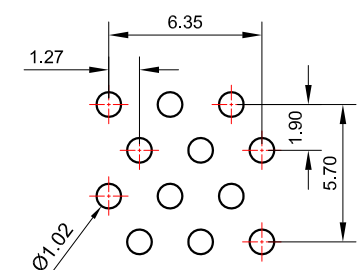
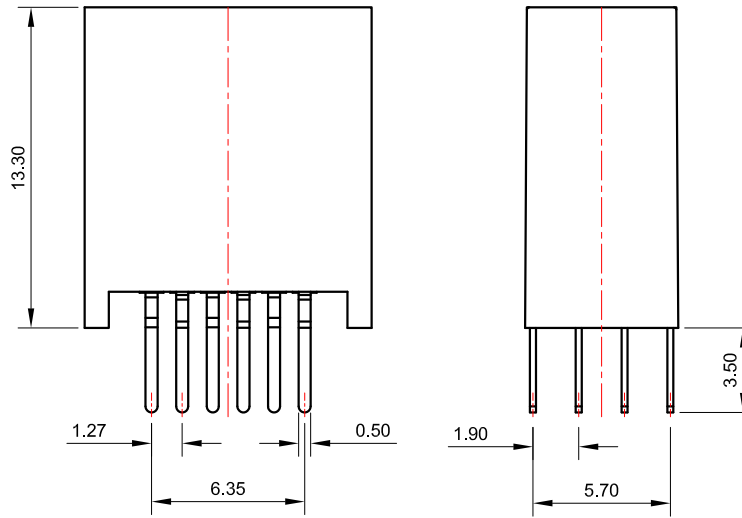
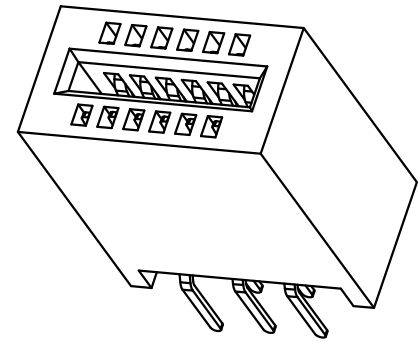
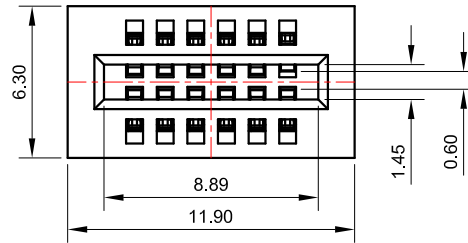
## NOTES:

1. FINISH:
  - 1.1 HOUSING: LCP BLACK,UL94V-0.
  - 1.2 CONTACT: PHOSPHOR BRONZE,GOLD (SEE P/N) PLATED IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
  - 2.1 CURRENT RATING:3A;
  - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC/MINUTE.
  - 2.3 CONTACT RESISTANCE: 30mΩ MAX.
  - 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
  - 2.5 OPERATION TEMPERATURE:-40°C TO +105°C.

## 3.ORDER INFORMATION:

61F1- 012 XX 133 C 01

Pin数码	端子电镀:	塑胶高度:	包装方式:
012=2x6PINS	S1=1u" Gold/Tin S2=3u" Gold/Tin S3=5u" Gold/Tin S4=10u" Gold/Tin S5=15u" Gold/Tin S6=30u" Gold/Tin	133=13.3mm	C=TRAY



RECOMMENDED PCB LAYOUT(TOP SIDE)  
PCB BOARD TOLFRANCF±0.05

						OPERATION	DRAW	FDL	2019.08.30	<b>SOLEPIN</b> 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
						X.X ±0.40	DESIGN	Jensen	2019.08.30				
						X.XX ±0.25	CHECK	Jack	2019.08.30				
						X.XXX ±0.15	APPROVE	Andy	2019.08.30				
AO		NEW				Angle ±3°				SHEET	1/2	TITLE:	1.27mm SLOT 180° DIP
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE		DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-229